

60V/2Ω@10V N-Channel MOSFET

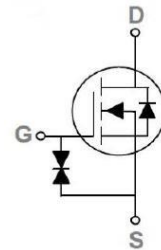
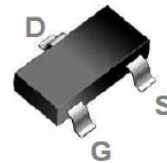
Features

- $V_{DS(max)}=60V$
- $I_D(max)=0.3A$
- $R_{DS(ON)}=2\Omega(max)@V_{GS}=10V$
- $R_{DS(ON)}=3\Omega(max)@V_{GS}=4.5V$
- Improved dv/dt capability
- Green Device Available
- Fast switching
- G-S ESD Protection Diode Embedded
- ESD Rating: 2000V HBM

Applications

- MB / VGA / Vcore
- Hand-Held Instrument
- Load Switch

SOT23-3S Pin Configuration



Maximum Ratings (Tc = 25°C, Unless Otherwise Noted)

Parameters	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current - Continuous(TC=25°C)	I_D	0.3	A
Drain Current - Continuous(TC=100°C)		0.2	A
Drain Current - Pulsed	I_{DM}^1	1.2	A
Power Dissipation(TC=25°C)	P_D	0.35	W
Power Dissipation - Derate above 25°C		0.003	W/°C
Storage Temperature Range	T_{STG}	-55~ 150	°C
Operating Junction Temperature Range	T_J	-55~ 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Typ.	Unit
Thermal Resistance Junction to ambient	$R_{\theta JA}$	357	---	°C/W

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.



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Electrical Characteristics(T_j = 25℃, Unless Otherwise Noted)

Off Characteristics						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain to Source Breakdown Volage	BV _{DSS}	V _{GS} =0V, I _D =250μA	60	---	---	V
BV _{DSS} Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25℃ , I _D =1mA	---	0.04	---	V/℃
Drain-Source Leakage Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V, T _J =25℃	---	---	1	μA
		V _{DS} =48V, V _{GS} =0V, T _J =125℃	---	---	10	μA
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	---	---	±100	nA
On Characteristics						
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =0.5A	---	---	2	Ω
		V _{GS} =4.5V, I _D =0.2A	---	---	3	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	---	2.5	V
V _{GS} (th) Temperature Coefficient	ΔV _{GS(th)}		---	-4	---	mV/℃
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =0.1A	---	0.24	---	S
Dynamic And Switching Characteristics						
Total Gate Charge ^{2,3}	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =0.2A	---	1.1	2	nC
Gate-Source Charge ^{2,3}	Q _{gs}		---	0.1	0.2	
Gate-Drain Charge ^{2,3}	Q _{gd}		---	0.23	0.5	
Turn-on Delay Time ^{2,3}	T _{d(on)}	V _{DD} =30V, I _D =0.2A V _{GS} =10V, R _{GEN} =6Ω	---	3	6	nS
Turn-on Rise Time ^{2,3}	T _r		---	5	10	
Turn-off Delay Time ^{2,3}	T _{d(off)}		---	14	27	
Turn-off Fall Time ^{2,3}	T _f		---	9	17	
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, F=1MHz	---	30.6	45	pF
Output Capacitance	C _{oss}		---	5.5	10	
Reverse Transfer Capacitance	C _{rss}		---	4	8	
Drain-Source Diode Characteristics And Maximum Ratings						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Continuous Source Current	I _S	V _G =V _D =0V,	---	---	0.3	A
Pulsed Source Current	I _{SM}	Force Current	---	---	1.2	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25℃	---	---	1	V

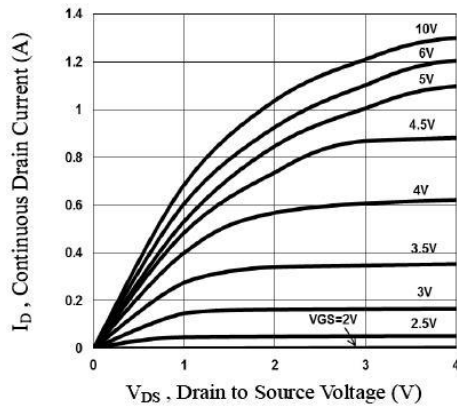


Fig.1 Output Characteristics

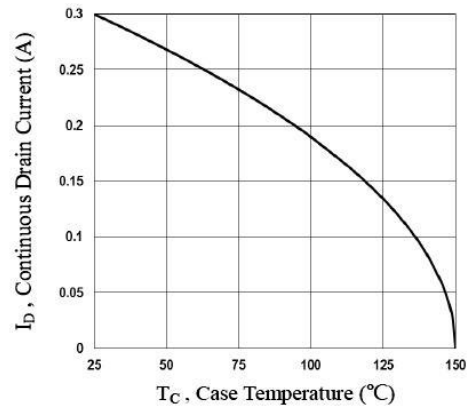


Fig.2 Continuous Drain Current vs. T_C

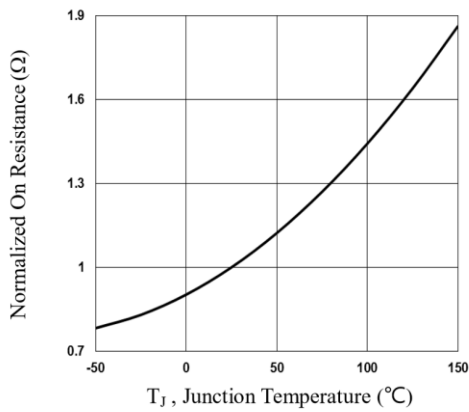


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

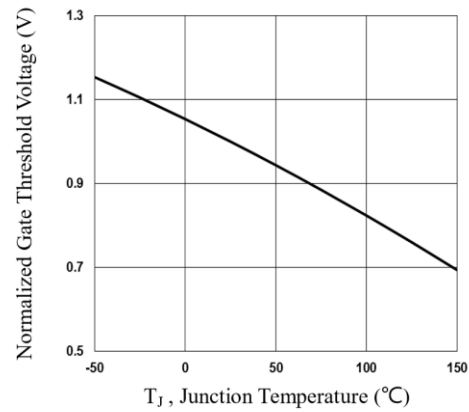


Fig.4 Normalized V_{th} vs. T_J

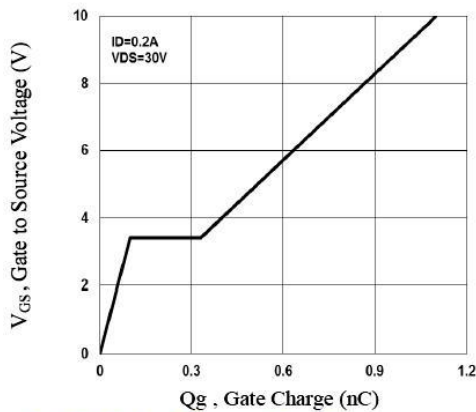


Fig.5 Gate Charge Waveform

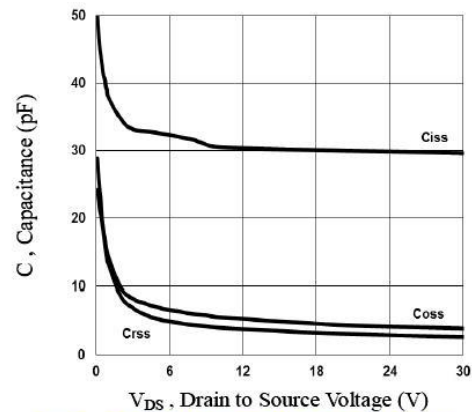


Fig.6 Capacitance Characteristics

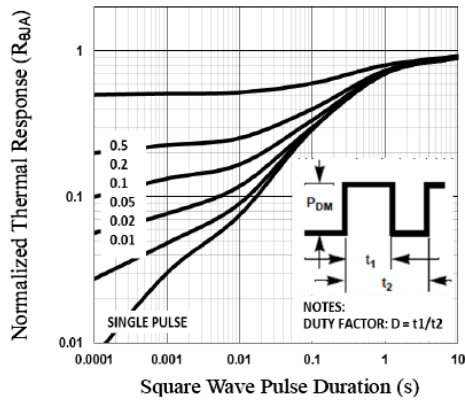


Fig.7 Normalized Transient Impedance

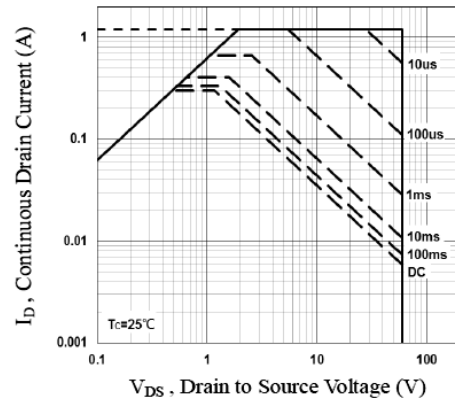


Fig.8 Maximum Safe Operation Area

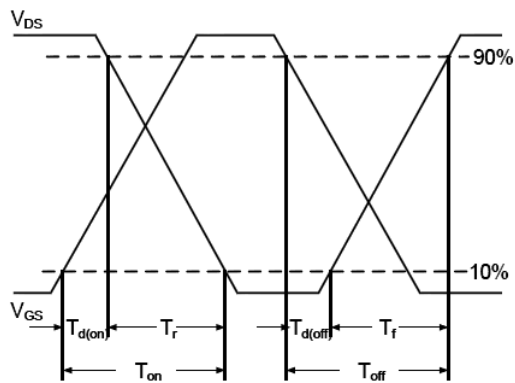


Fig.9 Switching Time Waveform

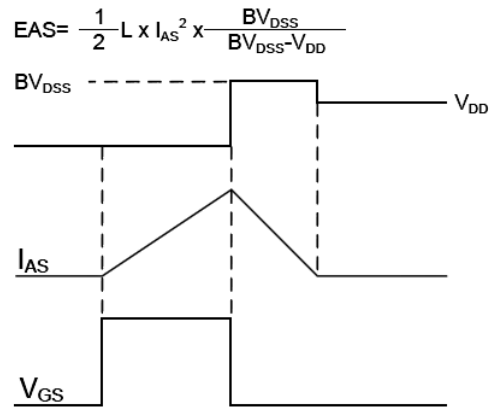
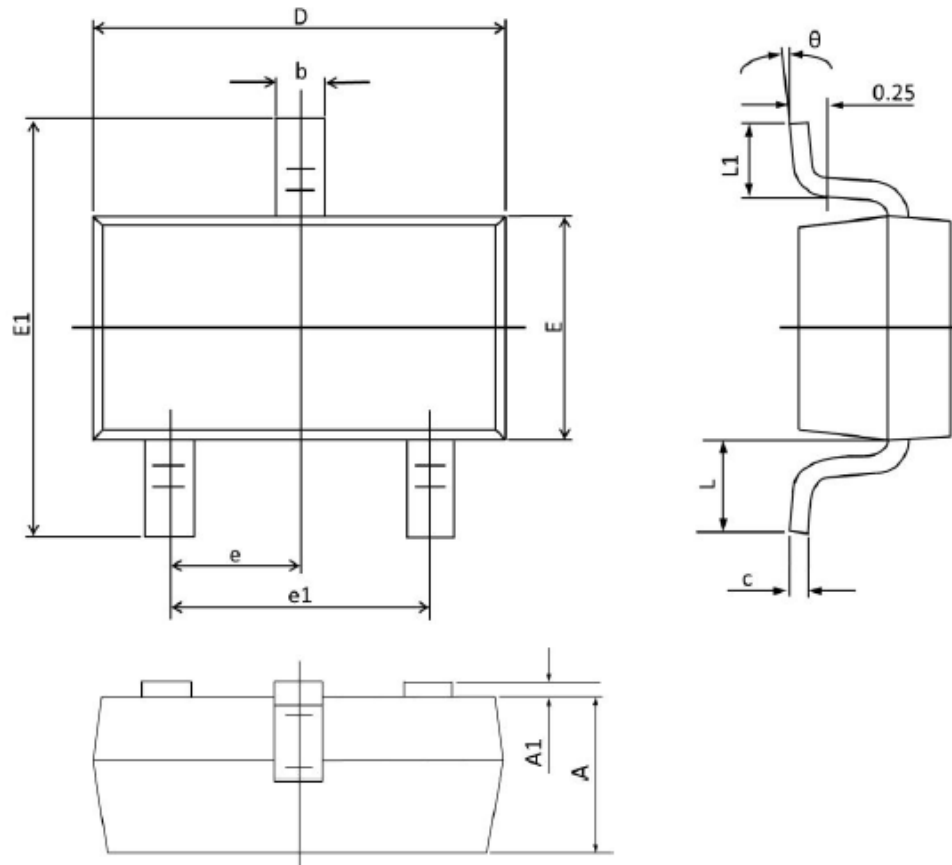


Fig.10 EAS Waveform

SOT 23-3S PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.003	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°